

Draft dated 6 August 2006

PRELIMINARY MEETING AGENDA – CE-2.9 SUBCOMMITTEE ON TEST PROCEDURES 28 – 29 September 2006, RENO, NV

1. Approval of the 24 –25 April 2006 Minute

2. SPECIFICATIONS BY PROJECT NUMBERS

"If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting".

A. SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research is sponsor)
To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

B. SP-4970: EIA-540DAAA-A: Detail, DIP
Sent to EIA for EDEC approval.

C. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector
Sent to EIA for EDEC approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA
To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

E. SP-4982-1: EIA-5400000A: Generic
Approved for EDEC ballot at the April 2006 meeting.

F. SP-5055: Replacement document for EIA-676-A Detail, SFF 1.8 inch (45.7 mm) Disk Drives
Standard published June 2006.

G. SP-5056: EIA-674: Detail, SFF 1.8" Disk Drives
Sent to EIA for EDEC approval.

H. SP-5058-A: EIA-720: Detail, SFF 2.5" Disk Drives
Awaiting results of 29 May 2006 ballot expiration.

I. SP-5059: EIA-677: Detail, SFF Power Connector Pin Dimensions
Approved for EDEC ballot at the April 2006 meeting.

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J. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

Approved for EDEC ballot at the April 2006 meeting.

K. SP-5114 as follows:

- 540C000: Sectional Relay Sockets
- 540CA00: Blank, Relay Sockets
- 540CAAA: Detail, 10A Relay Socket
- 540CAAB: Detail, 5A Relay Socket

Approved for EDEC ballot at the April 2006 meeting.

3. SPECIFICATIONS AWAITING PROJECT NUMBERS

A. EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

4. NEW BUSINESS

Prepared by
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